



TN-100 R1 AHA 09/24/01

ISO 9602

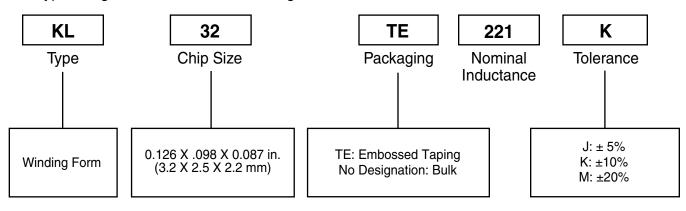
Chip Inductors Type KL32 Series

1. Scope

This specification applies to Chip Inductors (KL32) produced by KOA Corporation.

2. Type Designation

The type designation shall be the following form:



3. Rating

Item	Ratings			
Nominal Inductance Range (µH)	0.005 μH ~ 330 μH (E-12 series)			
Nominal Inductance Tolerance				
Quality Factor (typ.)				
Self Resonant Frequency (typ.) (MHz)	The rating shall be shown in the Table-1.			
DC Resistance (typ.) (Ω)				
Allowable Current (max.) (mA)				
Measuring Frequency (MHz)				
Operating Temperature Range (°C)	-25°C ~ +100°C			
Storage Temperature Range (°C)	-40°C ~ +100°C			
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Rating Table-1

Ordering Code*	Nominal Inductance (µH)	Inductance Tolerance	Quality Factor (Min.)	Self Resonant Frequency (Min.) (MHz)	DC Resistance (Max.) (Ω)	Allowable DC Current (Max.) (mA)	Measuring Frequency (MHz)
KL32TE005M	0.005	M (± 20%)	11	2700	0.12		
KL32TE010	0.010		15	2500	0.13		
KL32TE012	0.012		17	2300	0.14		
KL32TE015	0.015	K (± 10%)	19	2100	0.16		
KL32TE018	0.018	M (± 20%)	21	1900	0.18		
KL32TE022	0.022		00	1700	0.20		
KL32TE027	0.027	1	23	1500	0.22		100
KL32TE033	0.033		05	1400	0.24		100
KL32TE039	0.039		25	1300	0.27		
KL32TE047	0.047			1200	0.30		
KL32TE056	0.056	1	26	1100	0.33		
KL32TE068	0.068	1	07	1000	0.36		
KL32TE082	0.082		27	900	0.40	450	
KL32TER10	0.10		28	700	0.44		
KL32TER12	0.12			500	0.22		
KL32TER15	0.15			450	0.25		
KL32TER18	0.18	1		400	0.28		
KL32TER22	0.22	1		350	0.32		
KL32TER27	0.27			320	0.36		
KL32TER33	0.33	1		300	0.40		25.2
KL32TER39	0.39			250	0.45		
KL32TER47	0.47	J (± 5%)		220	0.50		
KL32TER56	0.56	K (± 10%)		180	0.55		
KL32TER68	0.68	M (± 20%)		160	0.60		
KL32TER82	0.82			140	0.65		
KL32TE1R0	1.0			120	0.70	400	
KL32TE1R2	1.2	1	30	100	0.75	390	
KL32TE1R5	1.5			85	0.85	370	
KL32TE1R8	1.8			80	0.90	350	
KL32TE2R2	2.2			75	1.0	320	
KL32TE2R7	2.7			70	1.1	290	
KL32TE3R3	3.3	1		60	1.2	260	7.96
KL32TE3R9	3.9			55	1.3	250	
KL32TE4R7	4.7			50	1.5	220	
KL32TE5R6	5.6			47	1.6	200	
KL32TE6R8	6.8			43	1.8	180	
KL32TE8R2	8.2			40	2.0	170	
KL32TE100	10	1		36	2.1	150	2.52

: Inductance tolerance (J, K or M)

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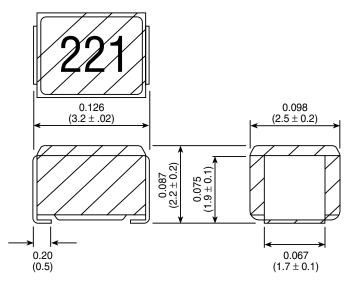


Rating Table-1 Continued

Ordering Code*	Nominal Inductance (µH)	Inductance Tolerance	Quality Factor (typ.)	Self Resonant Frequency (typ.) (MHz)	DC Resistance (typ.) (Ω)	Allowable DC Current (typ.) (mA)	Measuring Frequency (MHz)								
KL32TE120	12			33	2.5	140									
KL32TE150	15			30	2.8	130									
KL32TE180	18			27	3.3	120									
KL32TE220	22			25	3.7	110									
KL32TE270	27		30	20	5.0	80									
KL32TE330	33		30	17	5.6	70	2.52								
KL32TE390	39			16	6.4	65									
KL32TE470	47	J (± 5%) K (± 10%) M (± 20%)	K (± 10%)			1(+ 5%)]] (+ 5%)					15	7.0	60	
KL32TE560	56						13	8.0	55						
KL32TE680	68				12	9.0	50								
KL32TE820	82			IVI (± 20 %)	IVI (± 20 %)	IVI (± 20 /0)	IVI (± 20 /0)	IVI (± 20 /0)	W (± 20 /0)	IVI (± 20 /8)		11	10	45	
KL32TE101	100			10	10	40									
KL32TE121	120			10	11	70									
KL32TE151	150			8	15	65									
KL32TE181	180		20	7	17	60	0.796								
KL32TE221	220			/	21										
KL32TE271	270			6	28	50									
KL32TE331	330			5	34										

: Inductance tolerance (J, K or M)

4. Dimensions



Dimensions: Inches (mm) Weight: Approximately 50 mg

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5. Marking

Marking Method

The nominal inductance shall be expressed in " μ H" and consist of a number of three figures. No tolerance of inductance shall be indicated.

0.005 to 0.082µH

The three figures express three decimal places.

0.10 to 8.2µH

A decimal point replaced by an alphabetical letter "R" shall be significant figures.

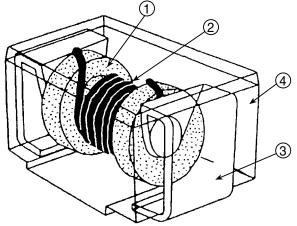
10 to 330µH

The first two figures are significant figures while the last figure shall show the number zero.

(Example of marking) 005 → 0.005µH 1R0 → 1.0µH 010 → 0.010µH 100 → 10µH R10 → 0.10µH

101 → 100µH

6. Construction



No.	Name	Material
1	Magnetic Core	High stability ferrite core
2	Winding Material	Polyurethane copper wire
3	Electrode Terminal	Solder plated high cond. heat resistant copper alloys
4	Mold Enclosure	Low stress epoxy resin system (UL94-VO)

7. Measurement Method of L and Q

Nominal Inductance Range (µH)	Measurement Method	Measuring Frequency (MHz)
0.005 ~ 0.10		100
0.12 ~ 0.82	Please see Method-1	25.2
1.0 ~ 8.2		7.96
10 ~ 82	Please see Method-2	2.52
100 ~ 330	Flease see Melliou-2	0.796

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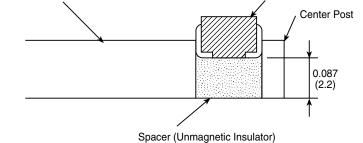




7. Measurement Method of L and Q *Continued*

Method-1

Test Equipment: Fixture: Electrical Length: Setting:	Hewlett Packard Hewlett Packard 2.10 cm Please see the fo	Spring clip fixt	
Slide C	Clip Terminal	KL32	, Center Post



Method-2

Test Equipment: Hewle Fixture: Hewle OSC Level: 0.3 V

Hewlett Packard LF Impedance analyzer 4192 Hewlett Packard Test fixture 16034E 0.3 V

8. Test Condition

Unless otherwise specified, the test shall be performed in accordance with JIS-C-5202 specifying marking measurements as follows: Ambient temperature: $20 \pm 15^{\circ}$ C Relative humidity: $65 \pm 20\%$

If there may be any doubt on results, measurements shall be made within the following limits:

Ambient temperature: $20 \pm 2^{\circ}C$ Relative humidity: $65 \pm 5\%$

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9. Reliability Data

9-1 Electrical Characteristics

ltem	Requirement	Test Method
DC Bias Characteristic	Δ L/L: Within - 10%	Measure inductance with application of rated current using LCR meter to compare it with the initial value.
Dielectric Withstanding Voltage	No fuming, flaming, or breakdown	5 seconds at DC 1000V between terminal 1 (one electrode of inductor) and terminal 2 (the thin copper wire which is wound around the inductor more than twice).
Insulation Resistance	More than 1000M Ω	Measure resistance immediately after 1 minute passed since DC 500V was applied between terminal 1 and 2.

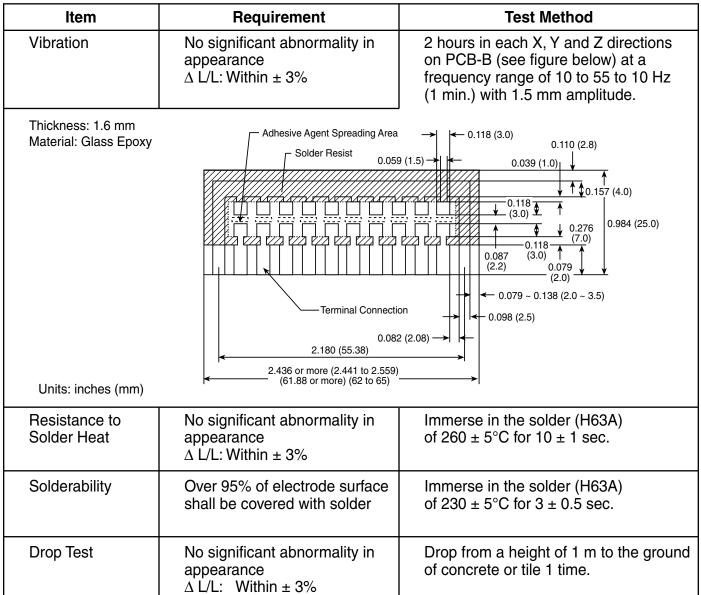
9-2 Mechanical Characteristics

Item	Requiremen	t	Test Method
Terminal Pull Strength	No damage		Terminals shall withstand a pull of 0.5kgf in a horizontal direction.
Terminal Bending Strength	No damage		Specimen shall be soldered on PCB-A (see figure below) and support by applying strength so that the bending width becomes 10 mm.
	Thickness: 1.6 mm Material: Paper Phenol		0.197 (5.0) Adhesive Agent Spreading Area
	(a) Board	✓////////////////////////////////////	2.2) → ← 0.197 (5.0) 3.937 (100.0) ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓
	(b) Install	1.77 (45.0	0) 1.77 (45.0) 0.063 (1.6) Solder Resist
	Units: inches (mm)	Soldering ——— Chip Inductor	ø 0.394 x 1.969 (ø 10 x 50) (Support Stick)

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9-2 Mechanical Characteristics *Continued*

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9-3 Environmental Characteristics *

Item	Requirement	Test Method
Low Temperature Life Test	Δ L/L: Within ± 5% Δ Q/Q: Within ± 20%	Store at -40 \pm 2°C for 1000 hours.
High Temperature Life Test	Δ L/L: Within ± 5% Δ Q/Q: Within ± 30%	Store at 100 \pm 2°C for 1000 hours.
Thermal Shock	Δ L/L: Within ± 5%	100 cycles between -25 \pm 2°C / 1 hour and +100 \pm 2°C.
Temperature Characteristic	Δ L/L: Within ± 10%	Measure Δ L/L at the temperature of between -25°C and +100°C as based on the temperature of 20°C.
Humidity	Δ L/L: Within ± 5% Δ Q/Q: Within ± 30%	Store at 40 ± 2°C, 90 to 95% RH for 1000 hours.
Humidity Loading Test	Δ L/L: Within ± 5% Δ Q/Q: Within ± 30%	Apply rated current continuously at $40 \pm 2^{\circ}$ C, 90 to 95% RH for 1000 hours.
High Temperature Loading Test	Δ L/L: Within ± 5% Δ Q/Q: Within ± 30%	Apply rated current continuously at $100 \pm 2^{\circ}$ C for 1000 hours.
Solvent Resistance	No outstanding damage and markings can be easily judged	According to MIL-STD-202F Method 215 (1990).

* Unless otherwise specified, at least one hour of recovery under the normal temperature and normal humidity after the test, followed by the measurement within two hours.

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10. Packaging

10-1 Bulk Packaging

Bulk products shall be packed 1,000 pieces in a poly bag. Marking item for bag shall be following form. (Marking item)

- (1) Type designation
- (3) Quantity
- (5) Manufacturer's name

- (2) Nominal inductance
- (4) Production lot number
- (6) Tolerance

10-2 Taping

The tapes for taping shall be embossed carrier tapes of .315" (8 mm) width and .157" (4 mm) pitch. The standard quantity per reel shall be 2,000 pieces.

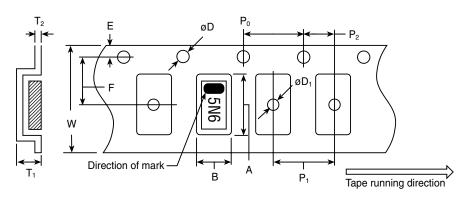
(1) Dimensions of carrier tape Dimensions in inches (mm)

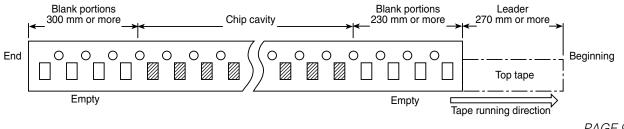
Α	.140 (3.55 ± 0.10)
В	.106 (2.70 ± 0.10)
W	.315 (8.00 ± 0.10)
Е	.069 (1.75 ± 0.10)
F	.138 (3.50 ± 0.05)
T ₁	.106 (2.70 ± 0.15)

T ₂	.011 (0.28 ± 0.05)
P₀	.157 (4.00 ± 0.10)
P ₁	.157 (4.00 ± 0.10)
P ₂	.079 (2.00 ± 0.05)
øD*	$.059 (1.50 \pm 0.1 \ 0)$
ØD ₁	$.039 (1.00 \pm 0.2 \ 0)$

The top tape requires a peel-off force of 15 to 60 gf.

* 20 pitches accumulation of sprocket holes shall be 80.00 ± 0.15 mm.







tech notes

(1) Type designation

(4) Production lot number (5) Manufacturer's name

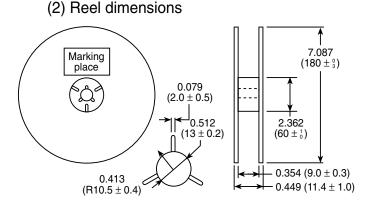
(2) Nominal inductance and tolerance

Dimensions in inches (mm)

(Marking item)

(3) Quantity

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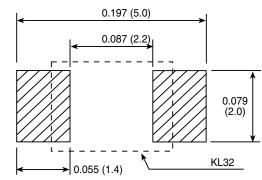


11. **Recommended Soldering Condition**

11-1 Dimensions of Standard Land

The following figure is recommended land dimensions.

When two or more chip inductors are closely mounted, they must be separated by means of solder resists to prevent excessive solder.



Dimensions in inches (mm)

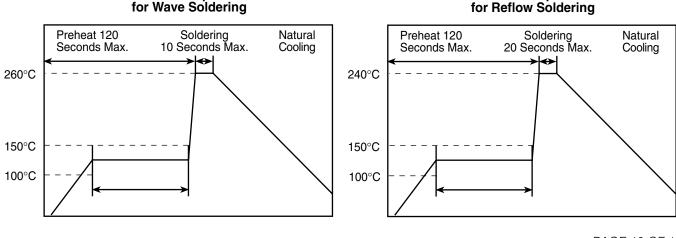
11-2 Soldering Condition

Wave soldering should be done at 260°C for less than 10 seconds. Reflow soldering should be done at 240°C for less than 20 seconds. (Please see the following figures.)

Recommended Temperature Profile

When using a soldering iron, temperature shall not exceed 350°C and within three seconds. Soldering iron time shall be allowed only one time. After soldering, chip inductors shall not be stressed excessively.

Recommended Temperature Profile



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12. Mounting

Placement force should not be excessive.

13. Recommended Washing Condition

Since this chip inductor is a coil of ultra-thin wire, it is susceptible to vibration.

If an ultrasonic cleaning unit is used for cleaning, check for any possibility of problem generation before practical use since such cleaning units considerably differ in vibration level and mode. Although the conditions differ depending on the printed board size, ultrasonic cleaning is generally used in the conditions described below as examples:

Ultrasonic power: Within 20W/1 Cleaning times: Within 5 minutes

14. Storage

Chip inductors should not be stored under high temperature and high humidity conditions. In particular, do not store *taping* where it is exposed to heat or direct sunlight. Otherwise, the packing material may be deformed, causing problems during mounting.

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